

ABSTRACT OF DISCLOSURE

A leadless plastic chip carrier is fabricated by selectively etching a leadframe strip to reduce a thickness of the strip at a portion thereof. Selectively masking the surface of the leadframe strip using a mask, follows selectively etching, to provide exposed areas of the surface at the portion and contact pad areas on leadframe the strip. At least one layer of metal is deposited on the exposed areas to define a die attach pad on the portion of the leadframe strip with reduced thickness and to define contact pads on the surface of the strip. At least one semiconductor die is mounted to the die attach pad, followed by wire bonding the at least one semiconductor die to ones of the contact pads. The at least one semiconductor die, the wire bonds, and the contact pads are covered with an overmold material and the leadframe strip is etched to thereby remove the leadframe strip. The leadless plastic chip carrier is singulated from the leadframe strip.